

## TECHNICAL DATA

### Teonex® Q83

#### ■ Characteristics

Extremely low heat shrinkage type treated by off-line process. Capability for soldering.

#### ■ Typical Applications

FPC, RFID, processing film for semiconductor, Flat cable

#### ■ Pretreatment

none

#### ■ Technical Data

Item	Unit	Q83 Type	Test method
Thickness	μm	50	JIS G2151
Tensile strength	MD	MPa	JIS C2318
	TD		
Tensile elongation	MD	%	JIS C2318
	TD		
Thermal Shrinkage (150 deg C × 30 mins.)	MD	%	JIS C2318
	TD		
Thermal Shrinkage (200 deg C × 10 mins.)	MD	%	JIS C2318
	TD		
Breakdown voltage	kV/mm	250	JIS C2318
Coefficient of friction	μs	-	JIS C7175
	μk		
Haze	%	15.0	JIS K7136

1.The information contained herein is believed to be reliable and correct.

2.Please refer to the MSDS for product safety data.

3.Information is presented without guarantee or warranty.